



## Material Content Data Sheet



Sales Product Name	2EDL23N06PJ			Issued		4. February 2020		
MA#	MA001192604							
Package	PG-DSO-14-49			Weight*		139.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.871	1.34	1.34	13450	13450
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		413	
	non noble metal	iron	7439-89-6	1.150	0.83		8265	
	non noble metal	copper	7440-50-8	46.675	33.56	34.44	335588	344369
wire	noble metal	gold	7440-57-5	0.258	0.19	0.19	1856	1856
encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1247	
	plastics	epoxy resin	-	9.368	6.74		67358	
	inorganic material	silicondioxide	60676-86-0	77.202	55.51	62.37	555078	623683
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8816	8816
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2204	2204
glue	plastics	acrylic resin	-	0.172	0.12		1237	
	noble metal	silver	7440-22-4	0.610	0.44	0.56	4385	5622
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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